



ALPHA & OMEGA
SEMICONDUCTOR

AO7414

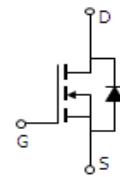
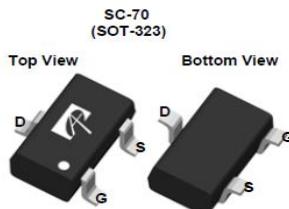
20V N-Channel MOSFET

General Description

The AO7414 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V, in the small SOT-323 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters.

Product Summary

V_{DS}	20V
I_D (at $V_{GS}=4.5V$)	2A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 62mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 70mΩ
$R_{DS(ON)}$ (at $V_{GS}=1.8V$)	< 85mΩ



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ^A	I_D	2	A
$T_A=70^\circ C$		1.5	
Pulsed Drain Current ^B	I_{DM}	25	
Power Dissipation ^A	P_D	0.35	W
$T_A=70^\circ C$		0.22	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	300	360	°C/W
Maximum Junction-to-Ambient ^A		340	425	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	280	320	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5	0.68	1	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	25			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=2\text{A}$ $T_J=125^\circ\text{C}$	50	62		$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=1.8\text{A}$	70	90		$\text{m}\Omega$
		$V_{GS}=1.8\text{V}, I_D=1\text{A}$	56	70		$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=2\text{A}$	66	85		$\text{m}\Omega$
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	0.7	1		V
I_S	Maximum Body-Diode Continuous Current				0.35	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$		260	320	pF
C_{oss}	Output Capacitance			48		pF
C_{rss}	Reverse Transfer Capacitance			27		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		3	4.5	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=2\text{A}$		2.9	3.8	nC
Q_{gs}	Gate Source Charge			0.4		nC
Q_{gd}	Gate Drain Charge			0.6		nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, R_L=5\Omega, R_{\text{GEN}}=6\Omega$		2.5		ns
t_r	Turn-On Rise Time			3.2		ns
$t_{D(\text{off})}$	Turn-Off DelayTime			21		ns
t_f	Turn-Off Fall Time			3		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=2\text{A}, dI/dt=100\text{A}/\mu\text{s}$		14	19	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=2\text{A}, dI/dt=100\text{A}/\mu\text{s}$		3.4		nC

A: The value of R_{JJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{JJA} is the sum of the thermal impedance from junction to lead R_{JUL} and lead to ambient.

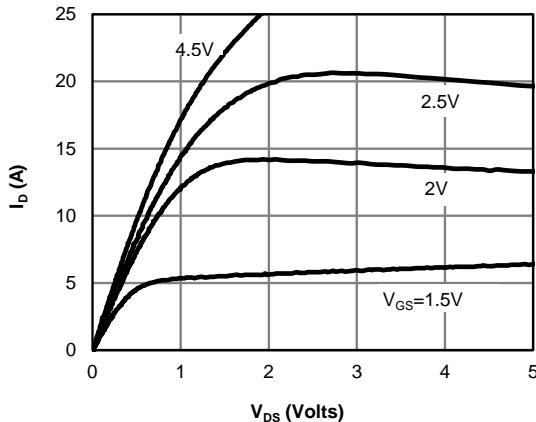
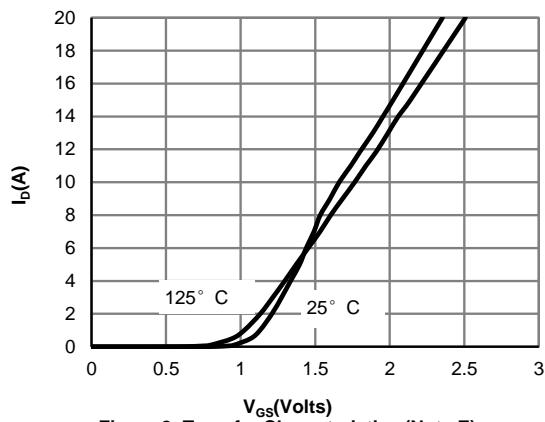
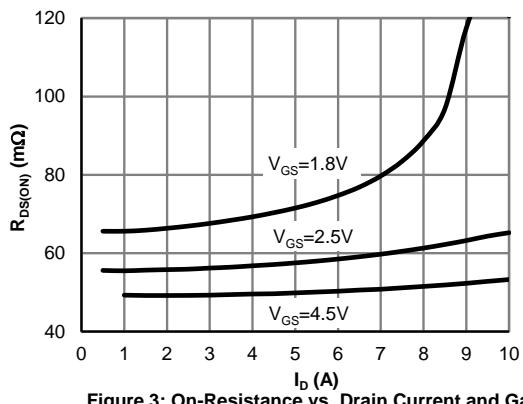
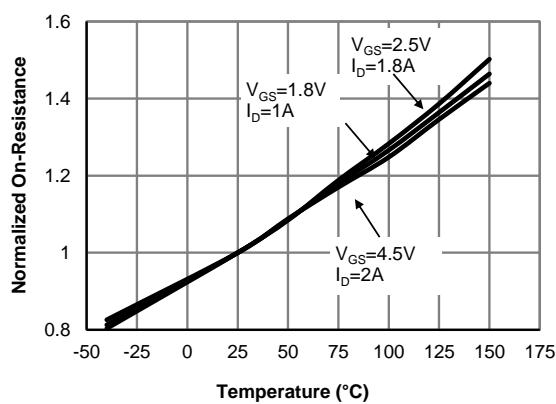
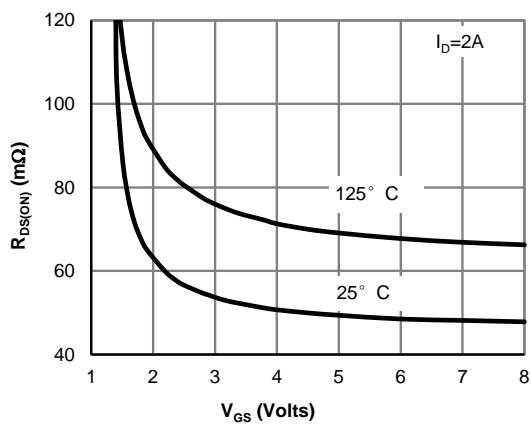
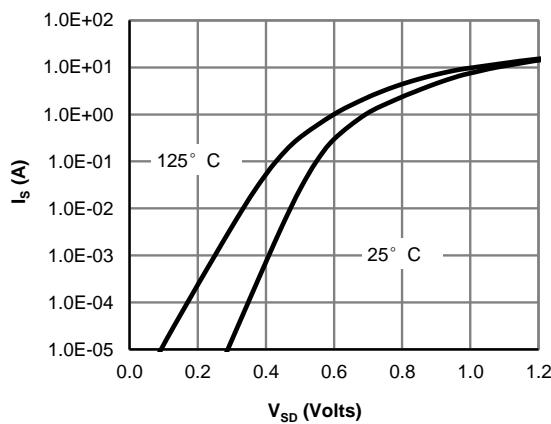
D: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

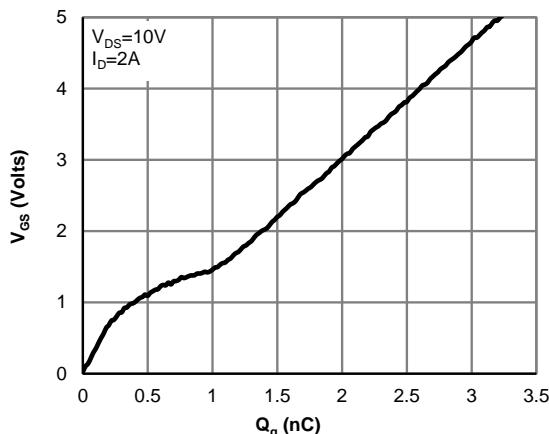
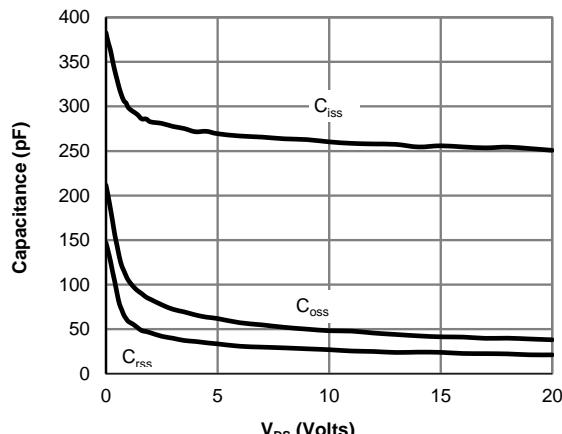
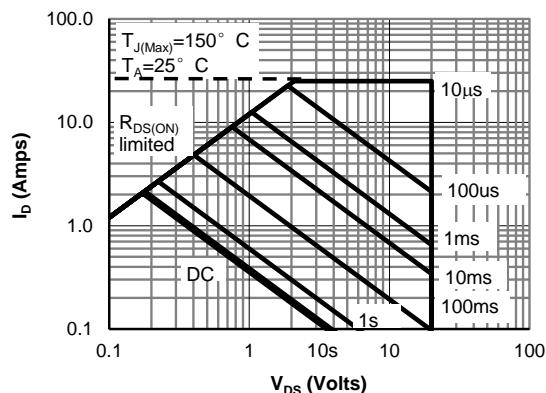
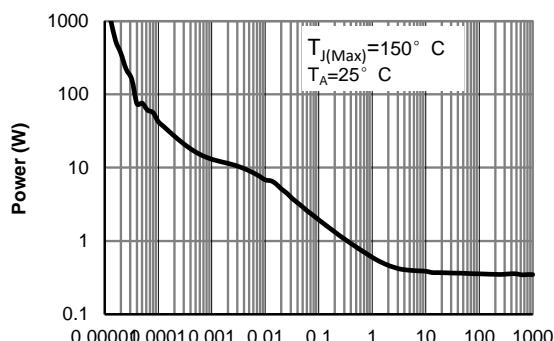
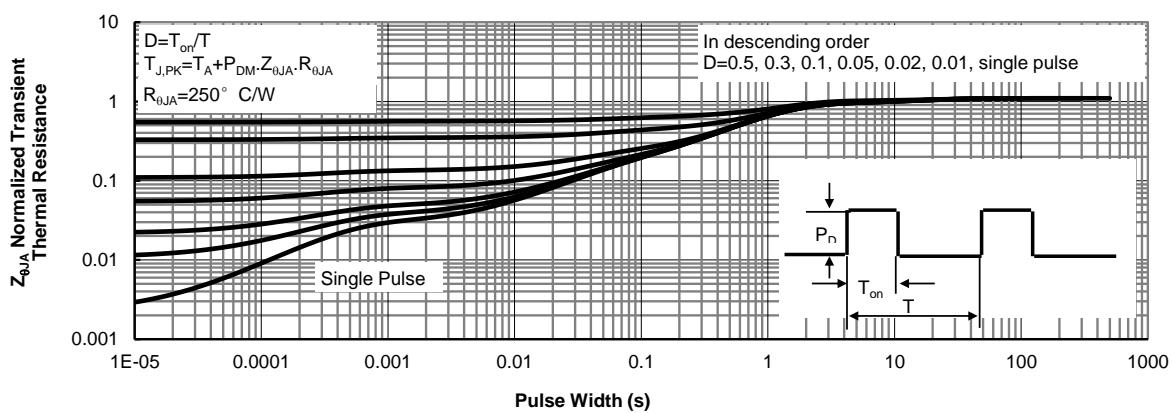
E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

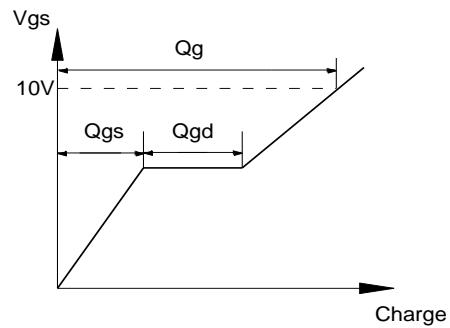
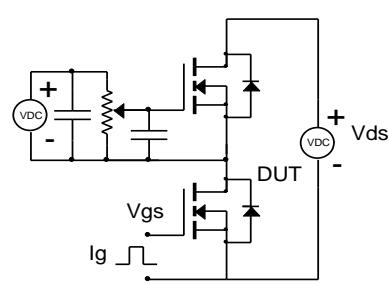
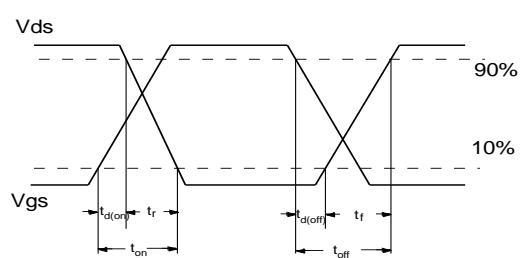
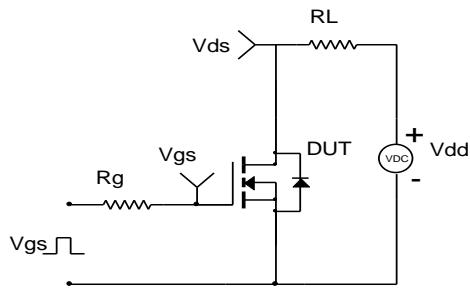
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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
